

### **REMARKS**

In the September 13, 2007 Office Action, claims 1-5 stand rejected in view of prior art. No other objections or rejections were made in the Office Action.

#### ***Status of Claims and Amendments***

In response to the September 13, 2007 Office Action, Applicants respectfully traverse the rejections and have included comments to support the traversals. Further, Applicants have amended claim 1 to correct and to clarify it, and have added new claim 6. Applicants wish to thank the Examiner for the examination of this application. Thus, claims 1-6 are pending, with claims 1-5 being the only independent claims. Reexamination and reconsideration of the pending claims are respectfully requested in view of above amendments and the following comments.

#### ***Rejections - 35 U.S.C. § 102***

In item 2 of the Office Action, claims 1-3 stand rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent Application Publication No. 2002/0004250 (Iketani et al.). In response, Applicants respectfully traverse the rejections and have included comments to support the traversals.

#### ***Claim 1***

In particular, independent claim 1 recites a carrier tape being formed as an exfoliate layer. On page 3 of the Office Action, it is stated that Iketani et al. disclose a carrier 50 (which can be seen in Figures 6A and so on of Iketani et al.). Applicants respectfully assert that in accordance with the specification of the instant application, (see the third full paragraph on page 3 of the written disclosure), a good interposer board is defined as a board “selected and cut out from an interposer board tape,” or, “selected and cut out from an interposer board tape excepting blank sections.” Since Applicants are allowed to be their

own lexicographer (MPEP §2111.01(IV)), Applicants respectfully assert that this meaning should be applied to the claims.

Thus, in light of this definition, as seen in Figures 7A and 7B and paragraphs [0051]-[0053] of Iketani et al., Applicants respectfully assert that the boards on the adhesive sheet 50 have not been selected and cut out from an interposer board tape as claimed. Applicants respectfully assert that since the boards on the adhesive sheet 50 have not been selected and cut out from an interposer board tape, they are not “good” as claimed. Further, referring to paragraph [0058] of Iketani et al., Applicants respectfully assert that the boards that are selected are placed in holes in the tape 41. However, in contrast to claim 1 of the present application, Applicants respectfully assert that this configuration lacks a carrier tape being formed as an exfoliate layer because the boards are not disposed on the tape 41 as claimed.

Moreover, Applicants respectfully assert that claim 1 recites that extended electrodes are formed on the base member. On page 3 of the Office Action, it is stated that item 26 constitutes the extended electrode, that item 33 constitutes an IC chip 33, and that items 25 and 26 constitute the base member. However, as seen in Figure 11A of Iketani et al., Applicants respectfully assert that only item 25 is provided for mounting the IC chip 33 and that there is a gap between items 25 and 26. Further, it is stated on page 3 of the Office Action that the Examiner has taken official notice that in the fabrication process, items 25 and 26 are formed as one piece and later cut. Thus, Applicants respectfully assert that the extended electrode 26 is not formed *on* the base member 25 as claimed, although it may be formed *from* the base member.

#### *Claims 2 and 3*

Applicants respectfully assert that claims 2 and 3 recite interposer board tape being obtained by forming the extended electrodes on a base member. The Office Action identifies

the extended electrodes as item 26 of Iketani et al. and the base member as items 25 and 26 of Iketani et al. Applicants respectfully assert that Iketani et al. fail to disclose or to suggest this feature for the reasons mentioned above. Further, Applicants respectfully assert that the interposer boards are disposed on the carrier tape that is obtained by forming an exfoliate layer on a base tape. On page 5 of the Office Action, item 45 is identified as the exfoliate layer. However, as seen in Figure 10B of Iketani et al., Applicants respectfully assert that the boards are not disposed on the tape 45.

Applicants respectfully assert that these structures are not disclosed or suggested by the prior art of record. It is well settled under U.S. patent law that for a reference to anticipate a claim, the reference must disclose each element of the claim within the reference. Therefore, Applicants respectfully submit that claims 1-3, as now amended, are not anticipated by the prior art of record. Withdrawal of these rejections is respectfully requested.

### ***Rejections - 35 U.S.C. § 103***

In item 4 of the Office Action, claims 4 and 5 stand rejected under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 6,378,774 (Emori et al.) in view of U.S. Patent Application Publication No. 2002/0004250 (Iketani et al.). In response, Applicants respectfully traverse the rejections and have included comments to support the traversals.

More specifically, independent claims 4 and 5 recite disposing interposer boards on a carrier tape, and the carrier tape being obtained by forming an exfoliate layer on one face of a base tape. The Office Action states, and Applicants agree, that Emori et al. fails to disclose peeling an interposer board from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, the interposer board being obtained by

mounting an IC chip, by forming extended electrodes each connected to a corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape as claimed. Thus, the Office Action relies on Iketani et al. to show these features. However, Applicants respectfully assert that the boards are not disposed on the carrier tape 45 for the reason stated above. Since neither reference shows this feature, Applicants respectfully assert that the combination of references also fails to disclose or to suggest this feature.

Applicants respectfully assert that this arrangement is not disclosed or suggested by the prior art of record. It is well settled in U.S. patent law that the mere fact that the prior art can be modified does not make the modification obvious, unless the prior art provides an apparent reason for the desirability of the modification. Accordingly, the prior art of record lacks any apparent reason, suggestion or expectation of success for combining the patents to create the Applicants' unique arrangement.

Therefore, Applicants respectfully request that these rejections be withdrawn in view of the above comments and amendments.

***New Claim 6***

Applicants have added new claim 6, which depends on claim 1. Applicants believe that claim 6 is allowable for the same reasons claim 1 is allowable. Further, Applicants believe that claim 6 is further allowable because it contains additional features.

Examination and consideration are respectfully requested.

***Prior Art Citation***

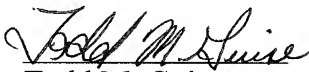
In the Office Action, additional prior art references were made of record. Applicants believe that these references do not render the claimed invention obvious.

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Appl. No. 10/582,897  
Amendment dated December 10, 2007  
Reply to Office Action of September 13, 2007

In view of the foregoing amendment and comments, Applicants respectfully assert that claims 1-6 are now in condition for allowance. Reexamination and reconsideration of the pending claims are respectfully requested.

Respectfully submitted,

  
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